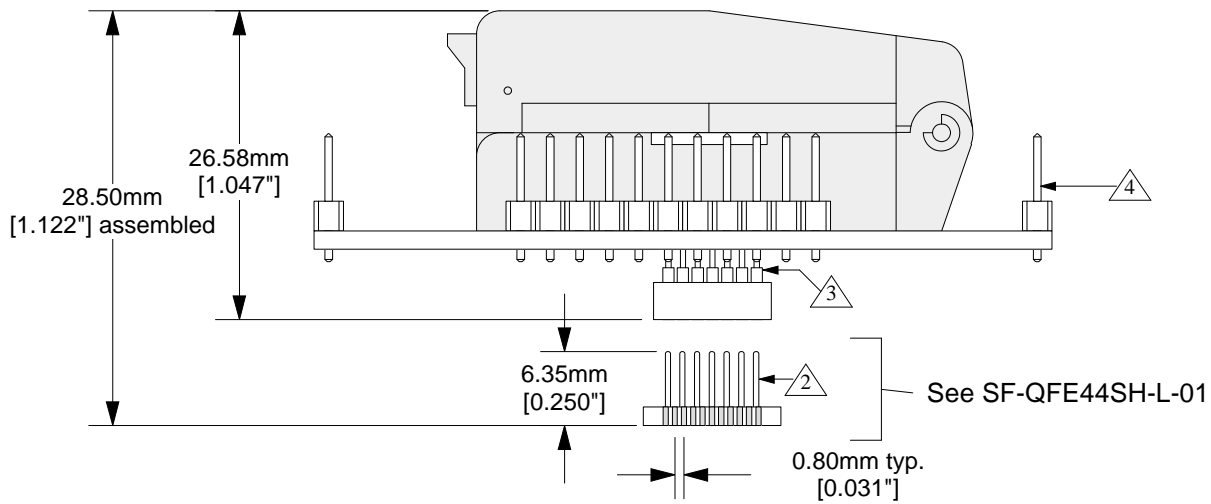


Top View




Side View

- ① Substrate: 1.59mm \pm 0.18mm [0.0625" \pm 0.007"] FR4/G10 or equivalent high temp material. 17 μ m [1/2 oz.] Cu clad. SnPb plating.
- ② Pins: material- Brass Alloy 360 1/2 hard; finish- 0.25 μ m [10 μ] Au over 1.27 μ m [50 μ] Ni (min.).
- ③ Pins: shell material- Brass Alloy 360 1/2 hard; finish- 0.25 μ m [10 μ] Au over 1.27 μ m [50 μ] Ni (min.). Contact material- BeCu; finish 0.25 μ m [10 μ] Au over 2.54 μ m [100 μ] Ni (min.).
- ④ Test points: material- Phosphor Bronze; plating- Sn over 1.27 μ m [50 μ] Ni. Gold flash on contact end.

Description: Carrier Adaptor (CA), QFP

44 position QFP ZIF socket with test points to 44 position QFP surface mount foot (leadless). Two-piece part utilizes pluggable mini-grid array (MGA) intermediate interface. Additional surface mount feet, SF-QFE44SH-L-01, are available separately. Interconnections are 1:1.

Tolerances: diameters \pm 0.03mm [\pm 0.001"], PCB perimeters \pm 0.13mm [\pm 0.005"], PCB thicknesses \pm 0.18mm [\pm 0.007"], pitches (from true position) \pm 0.08mm [\pm 0.003"], all other tolerances \pm 0.13mm [\pm 0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

CA-QFE44SH-L-Z-T-01 Drawing		Status: Released	Scale: 2:1	Rev: A
 <p>© 2001 IRONWOOD ELECTRONICS, INC. PO BOX 21151 ST. PAUL, MN 55121 Tele: (651) 452-8100 www.ironwoodelectronics.com</p>	Drawing: E Smolentseva		Date: 11/13/01	
	File: CA-QFE44SH-L-Z-T-01 Dwg.mcd		Modified:	